



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

A

B

C

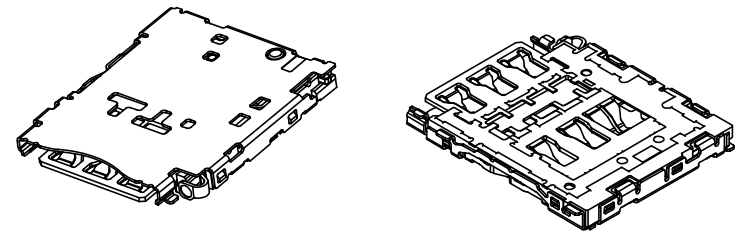
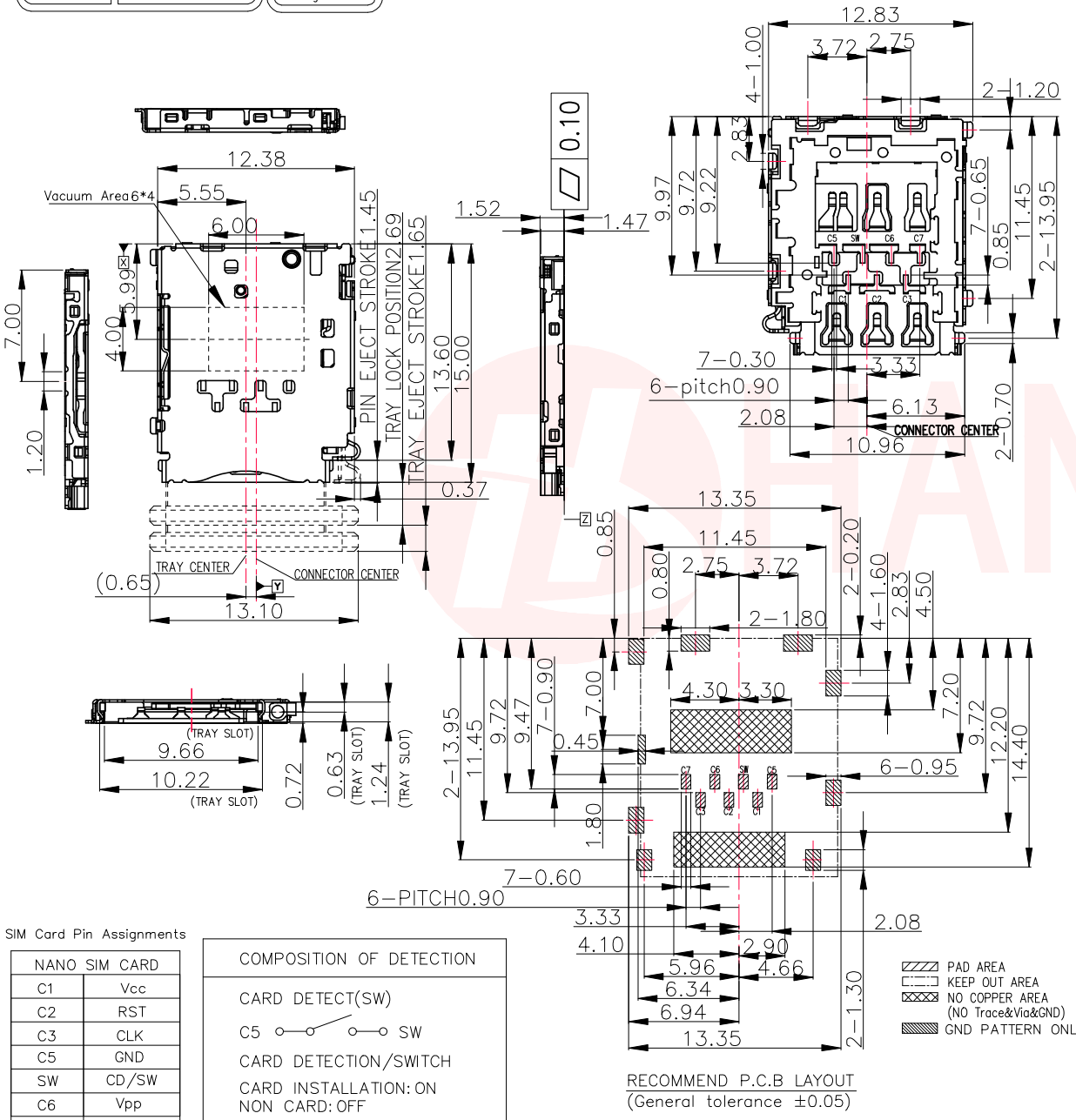
D

A

B

C

D

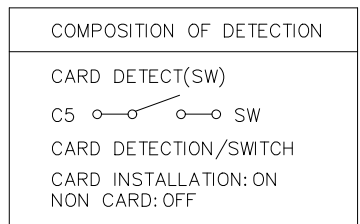


NOTE:

- Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
 - 1-3 Cover: SUS304-H T=0.15±0.03mm
- Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 1u" Min.
 - Solder area: Gold 0.8u" Min.
 - Underplating: Ni overall 50u" Min.
 - 2-2 Cover:
 - Underplating: Ni overall 30u" Min.
 - Solder area: Gold 0.8u" Min.
- Specification:
 - 3-1. Current Rating : 0.5A max.
 - 3-2. Contact Resistance: 50 mOhms max
 - 3-3. Insulation Resistance: 1000 MOhms min./500VDC
 - 3-4. Dielectric Withstanding Voltage: 500 V AC/1minute
 - 3-5. Operating Temperature: -40°C to +85°C
 - 3-6. Mating Cycles: 5000 Insertions
- Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
- Part Must Comply Taisol HF WD-3-I-091 Specification.
- Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X : ±0.35	X : ±2°
X.X : ±0.20	X.X : ±1°
X.XX : ±0.10	

东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	NANO SIM H1.5 CARD 卡座		
DWN	xiong	PART NO. SNO-1355	
CHKD	lee	SCALE: 1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET: 10F 1
			REV: A4

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